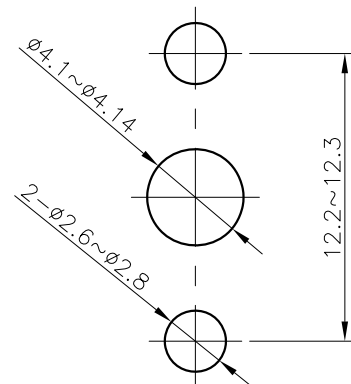
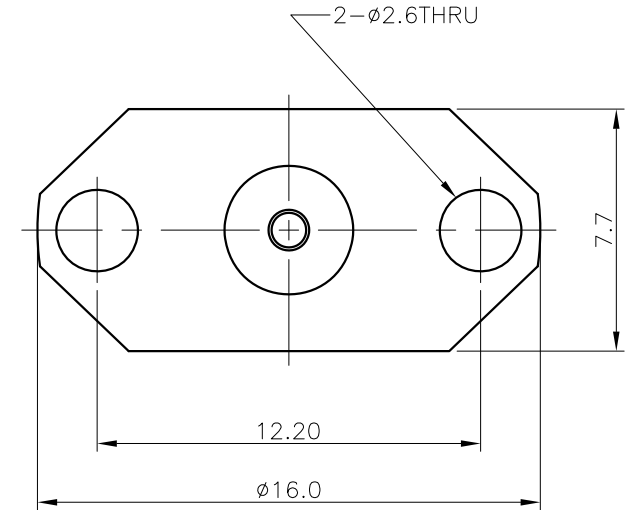
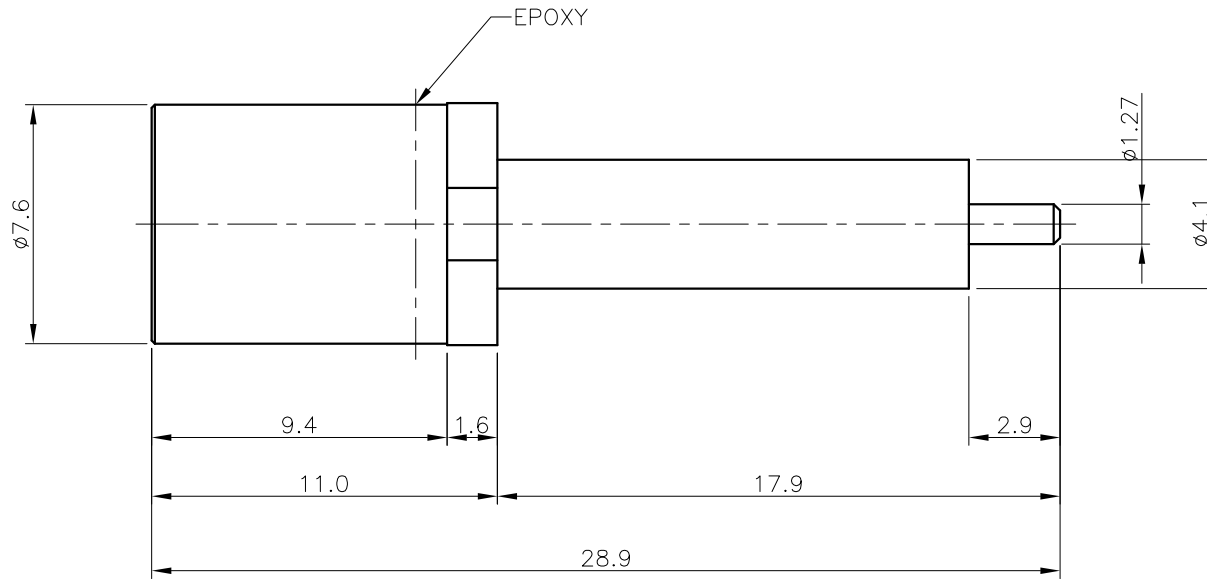


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
1 R	Initial Registration	S.H.KIM		2023.05.11.



PANEL HOLE SIZE

5	PIN COVER	1	MBsBD C3604BD-F	Gold Plate	DIB00026-5/1
4	PLATE SPRING	1	BeCu C17300	Gold Plate	DPS00002-5/1
3	INSULATOR	1	TEFLON		DIN03359-N/1
2	CONTACT	1	BeCu C17300	Gold Plate	DCT04385-5/1
1	BODY	1	MBsBD C3604BD-F	Nickel Plate	DBD04905-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.2	DATE 2023. 05. 11.			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017	
	Angle ±1°	APPROVED BY				
MATERIAL -		CHECKED BY			TITLE BMA50 SOLDER END JS-2H	
		DRAWN BY S.H.KIM				
FINISH -	SCALE 4/1	UNIT mm		A4	DWG NO. CN04112-7/1	
					REVISION I R SHEET 1 of 1	